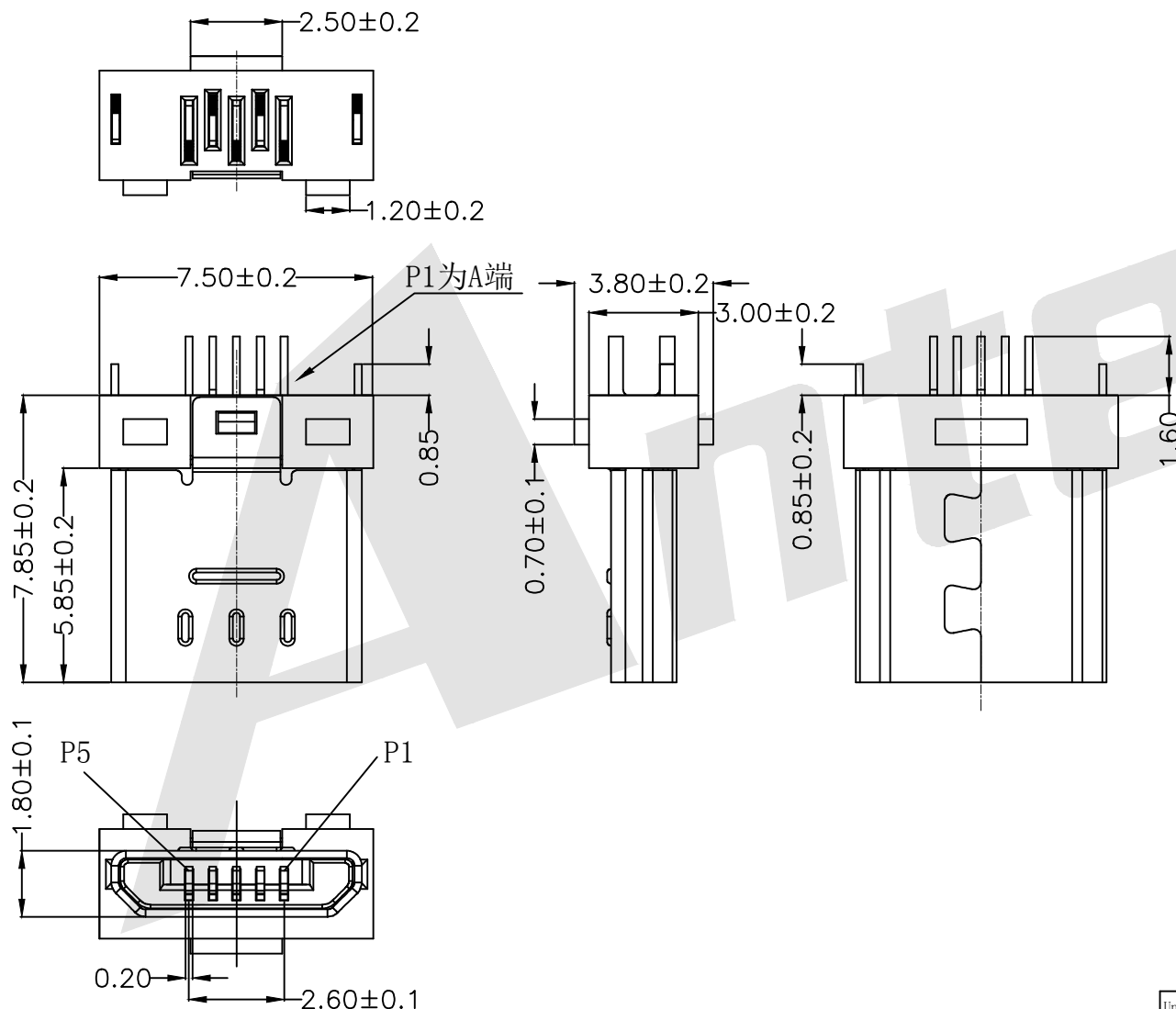


HSF



SPECIFICATIONS:

Current Rating: 1A Max
Contact Resistance: 50 milliohms MAX
Dielectric Withstanding Voltage: 100V AC AT Sea Level
Insulation Resistance: 100 MEGA ohms MIN
Housing: Temperature Thermoplastics, LCP UL 94V-0
Contact: Copper Alloy, Plated Gold in Mating Area; Tin On Solder Tails
Shell: Stainless Steel, Nickel/Plating

Ordering Code:

MUMS13 - X - X - X - X - X
① ② ③ ④ ⑤ ⑥

① Series No:

② Shell Material:

B: Brass I: Iron
S: stainless steel

③ Insulator Material:

P: PBT+30%GF
L: LCP

④ Contact Material:

B: Brass
P: phosphor copper

⑤ Contact Plating

G0: Gold flash
G1: 3u" Gold
G2: 5u" Gold
G3: 10u" Gold
G4: 15u" Gold
G5: 30u" Gold

⑥ Packing

A: Tray
B: Bag
C: Tube
D: Tape&Reel

Unless Otherwise specified tolerance
X. ±0.35 X.XX: ±0.20
X.X: ±0.25 X.XXX: ±0.15

SCALE: As Shown UNIT: mm
DRAW Lv Xun Hua DATE 04/06/2019
CHECK BobYang DATE 04/06/2019



ANTENK ELECTRONICS CO., LTD
Http://www.antenk.com
E-mail: sales@antenk.com

TITLE: MICRO USB B TYPE PLUG 5P Short
Body, Through Hole Type Dip=1.6mm

DRAWING NO: MUMS13-XXXXX

PRODUCT NO: MUMS13-XXXXX

REV

DESCRIPTION

DATE